

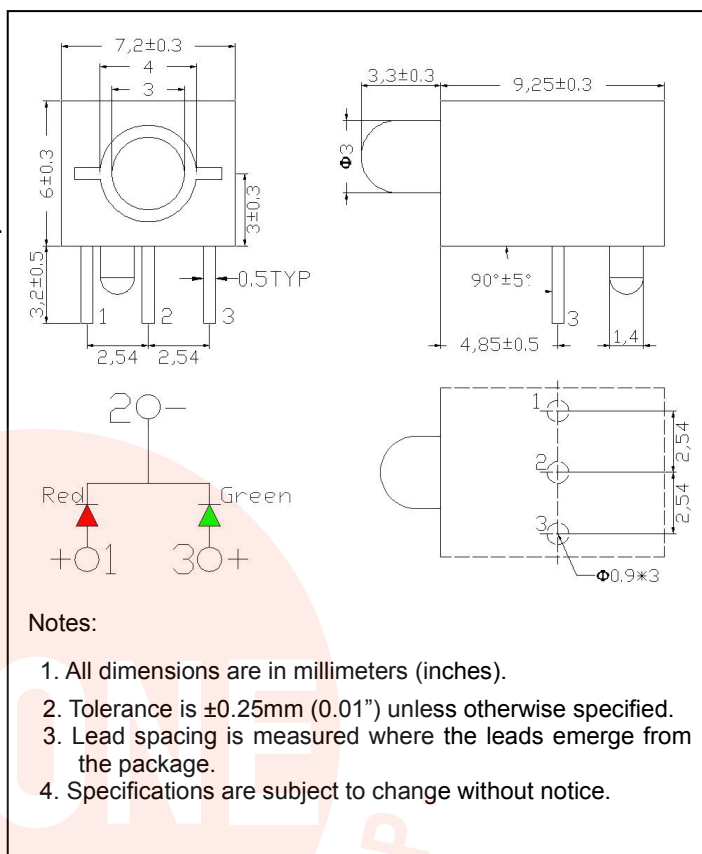
● Features:

1. Chip material: GaAsP/GaP(Red)
and GaP(Green)
2. Emitted color : Red and Green
3. Lens Appearance :White Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. This product don't contained restriction substance, compliance RoHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



● Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Red	Green	Unit
Power Dissipation	Pd	80	80	mW
Forward Current	I _F	30	30	mA
Peak Forward Current*1	I _{FP}	100	100	mA
Reverse Voltage	V _R	5		V
Operating Temperature	Topr	-40°C~80°C		
Storage Temperature	Tstg	-40°C~85°C		
Soldering Temperature	Tsol	260°C max (for 5 seconds)		
Hand Soldering Temperature	Tsol	350°C max(for 3 seconds)		

*1Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	Red Green	1.8 1.8	-	2.4 2.4	V
Luminous Intensity	I_v	$I_F=20\text{mA}$	Red Green	20 60	-	60 100	mcd
Reverse Current	I_R	$V_R=5\text{V}$	Red Green	-	-	10 10	μA
Peak Wave Length	λ_p	$I_F=20\text{mA}$	Red Green	-	-	-	nm
Dominant Wave Length	λ_d	$I_F=20\text{mA}$	Red Green	615 565	-	625 575	nm
Spectral Line Half-width	$\Delta\lambda$	$I_F=20\text{mA}$	Red Green	-	30 30	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	Red Green	-	60 60	-	deg

● Typical electro-optical characteristics curves

Red and Green

Fig.1 Relative intensity vs. Wavelength

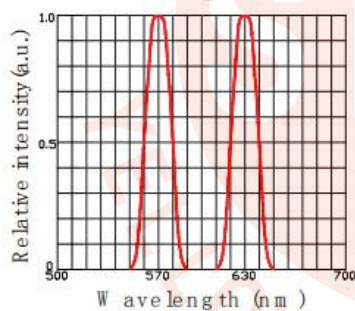


Fig.2 Forward current derating curve vs. Ambient temperature

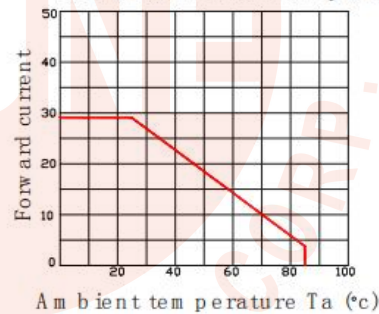


Fig.3 Forward current vs. Forward voltage

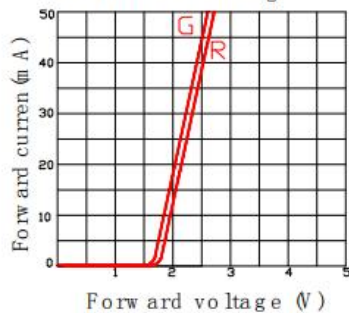


Fig.2 Relative luminous intensity vs. Ambient temperature

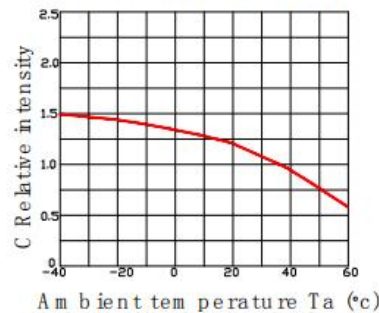


Fig.5 Relative luminous intensity vs. Forward current

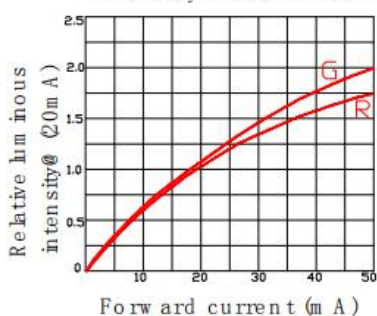
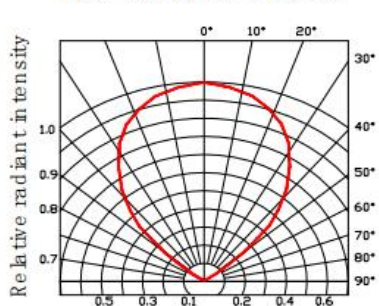
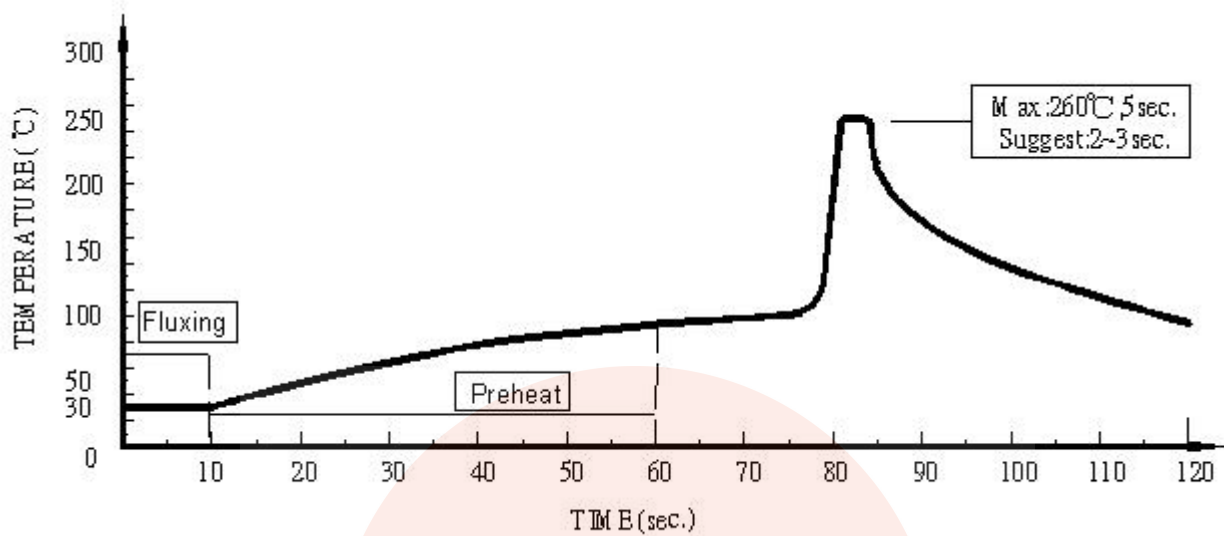


Fig.6 Radiation diagram



● DIP Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A: Max: 350°C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350°C

Within 2 sec. One time only

